

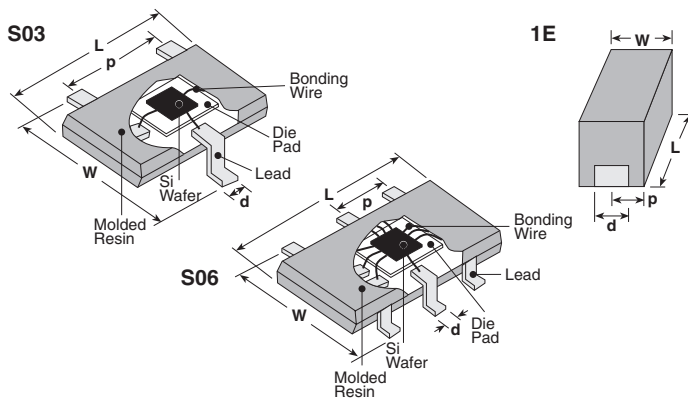
features

- (16kV) IEC 61000-4-2 rating
- Surface mount package
- High component density

applications

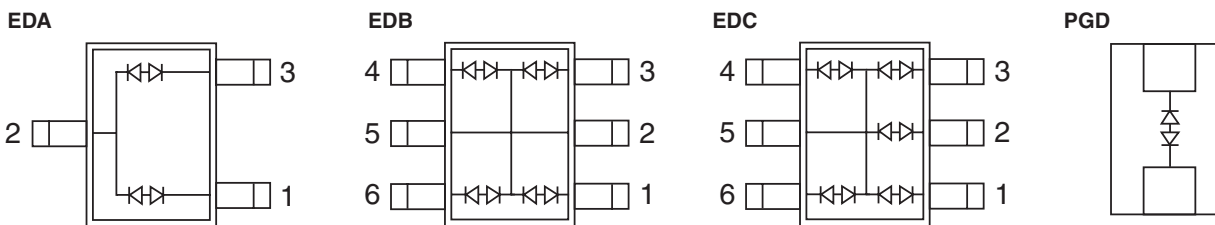
- ESD suppression
- Transient suppression

dimensions and construction



Package Code	Total Power	Pins	Dimensions inches (mm)				
			L ±0.2	W ±0.2	p ±0.1	Pkg Ht ±0.2	d ±0.05
S03	225mw	3	.115 (2.92)	.091 (2.30)	.075 (1.91)	.037 (0.95)	.017 (0.43)
S06	225mw	6	.115 (2.92)	.110 (2.80)	.037 (0.95)	.037 (0.95)	.017 (0.43)
1E	100mw	2	.043 (1.1)	.030 (0.75)	.015 (0.38)	.030 (0.75)	.014 (0.35)

circuit schematic



ordering information

New Part #	EDA	S03	T	TE	5V0
Type	EDA EDB EDC PGD	Package Code From table above	Lead Plating T: Sn	Packaging TE: 7" embossed plastic tape	Voltage 5V0 16V

For further information on packaging, please refer to Appendix C.

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

1/11/05

applications and ratings

Part Designation	Diode Breakdown Voltage $I_F = 1 \text{ ma}$	Leakage Current (Typ.)	Capacitance @ 1 Mhz	Channel Clamp Voltage 8kV H.B.M.	ESD Voltage Capability IEC 61000-4-2
EDA EDB	16V to 27V	$\pm 0.1 \mu\text{A}@14\text{V}$	2.0pF	$\pm 20\text{V}$	16kV Max.
EDC PGD	5.1V to 10V	$\pm 0.1 \mu\text{A}@5\text{V}$	1.5pF	$\pm 7\text{V Max.}^*$	16kV Max.

* Channel Clamp Voltage: 8kV event

application schematic

